

APPLICATION SERIAL NO.: 10/800,861

1. (Currently Amended) A wiring, comprising:

a first metal diffusion-preventing layer formed on [[a]] an insulating substrate;

a metal seed layer formed on the first metal diffusion-preventing layer;

a metal wiring layer formed on the metal seed layer; and

a second metal diffusion-preventing layer covering the exposed surface including the side surface of the multilayered structure having the metal seed layer and the metal wiring layer,

wherein the metal seed layer and the metal wiring layer are surrounded by the first metal diffusion-preventing layer and the second metal diffusion-preventing layer.

2. (Currently Amended) A wiring, comprising:

a first metal diffusion-preventing layer formed on [[a]] an insulating substrate;

a metal seed layer formed on the first metal diffusion-preventing layer;

a metal wiring layer formed on the metal seed layer; and

a second metal diffusion-preventing layer covering the exposed surface including the side surface of the multilayered structure having the metal seed layer and the metal wiring layer and the first metal diffusion-preventing layer,

wherein the metal seed layer and the metal wiring layer are surrounded by the first metal diffusion-preventing layer and the second metal diffusion-preventing layer.

3. (Currently Amended) A wiring, comprising:

a first metal diffusion-preventing layer formed on [[a]] an insulating substrate;

a metal wiring layer formed on the first metal diffusion-preventing layer; and

a second metal diffusion-preventing layer covering the exposed surface including the side surfaces of the metal wiring layer and the first metal diffusion-preventing layer, wherein the metal wiring layer is surrounded by the first metal diffusion-preventing layer and the

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second metal diffusion-preventing layer.

4. (Currently Amended) A display device having at least one of a wiring, comprising electrodes of driving elements arranged to form a matrix, the scanning lines connect to the driving elements, the and data lines, connected to the driving element being at least one of which is arranged so that it is surrounded by a first metal diffusion-preventing layer and a second metal diffusion-preventing layer.

5. (Currently Amended) The display device having ~~[[a]]~~ the wiring according to claim 4, wherein a transparent conductor layer or a metal layer is formed on the wiring with the second metal diffusion-preventing layer interposed therebetween.

6.-15. (Canceled)

16. (New) The wiring according to claim 1, wherein the insulating substrate is formed of one of glass, a quartz glass, ceramics, and a resin material.

17. (New) The wiring according to claim 1, wherein the first metal diffusion-preventing layer is a planar layer.

18. (New) The wiring according to claim 1, wherein the metal seed layer has a width that is smaller than a width of the first metal diffusion-preventing layer.

19. (New) The wiring according to claim 1, wherein the metal wiring layer has a width that is smaller than a width of the metal seed layer.

20. (New) The wiring according to claim 1, wherein the metal wiring layer has a width at a top surface thereof that is narrower than a width at a bottom surface thereof.

21. (New) The wiring according to claim 2, wherein the insulating substrate is formed of one of glass, a quartz glass, ceramics, and a resin material.

22. (New) The wiring according to claim 2, wherein the first metal diffusion-preventing layer is a planar layer.

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23. (New) The wiring according to claim 2, wherein the metal wiring layer has a width that is smaller than a width of the first metal diffusion-preventing layer.

24. (New) The wiring according to claim 2, wherein the metal wiring layer has a width that is smaller than a width of the metal seed layer.

25. (New) The wiring according to claim 2, wherein the metal wiring layer has a width at a top surface thereof that is narrower than a width at a bottom surface thereof.

26. (New) The wiring according to claim 3, wherein the insulating substrate is formed of one of glass, a quartz glass, ceramics, and a resin material.

27. (New) The wiring according to claim 3, wherein the first metal diffusion-preventing layer is a planar layer.

28. (New) The wiring according to claim 3, wherein the metal wiring layer has a width at a top surface thereof that is narrower than a width at a bottom surface thereof.

29. (New) The wiring according to claim 3, wherein the metal wiring layer has a width that is smaller than a width of the first metal diffusion-preventing layer.